# **USHIO** Applying Light to Life



Data Sheet

2020.05

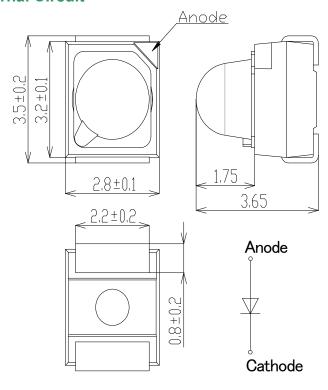
epitex

**PRELIMINARY** 

# SMT1200D-S1

1200nm High Performance Infrared TOP LED

## **Outline and Internal Circuit**



(Unit: mm)

#### **Features**

• Chip Material : InGaAsP

• Chip Dimension: 350um \* 350um

• Number of Chips : 1pce

• Peak Wavelength : 1200nm typ.

· Lead Frame Die: Silver Plated

Package Resin : PA6T

• Lens : Silicone Resin

## **Application**

## **Absolute Maximum Ratings (Tc=25°C)**

Item	Symbol	Ratings	Unit
Power Dissipation	PD	140	mW
Forward Current	lF	100	mA
Pulse Forward Current	IFP	1000	mA
Reverse Voltage	VR	5	V
Thermal Resistance	Rthjs	80	K/W
Junction Temperature	Tj	120	°C
Operating Temperature	Topr	-40 ~ +100	°C
Storage Temperature	Tstg	-40 ~ +100	°C
Soldering Temperature	TSOL	250	°C

<sup>‡</sup>Pulse Forward Current condition : Duty 1% and Pulse Width=10us.

## Optical and Electrical Characteristics (Tc=25°C)

(\*: 100% testing, \*\*: reference value)

Parameter	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage	VF		1.1	1.4	V	IF=50mA*
	VFP		2.2			IFP=1A**
Reverse Current	IR			10	uA	VR=5V*
Total Radiated Power	РО	6.5	10		mW	IF=50mA*
			64			IFP=1A**
Radiant Intensity	IE		53		mW/sr	IF=50mA**
			340			IFP=1A**
Peak Wavelength	λр	1170		1230	nm	IF=50mA*
Half Width	Δλ		80		nm	IF=50mA**
Viewing Half Angle	θ1/2		±9		deg.	IF=50mA**
Rise Time	tr		60		ns	IF=50mA**
Fall Time	tf		30		ns	IF=50mA**

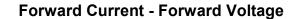
<sup>‡</sup> Radiated Power is measured by G8370-85.

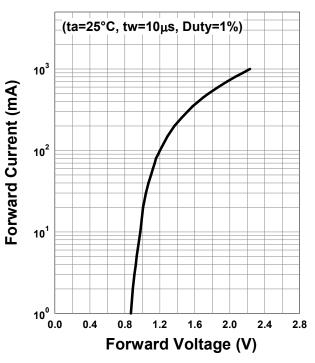
<sup>‡</sup>Soldering condition : Soldering condition must be completed with 5 seconds at 250°C.

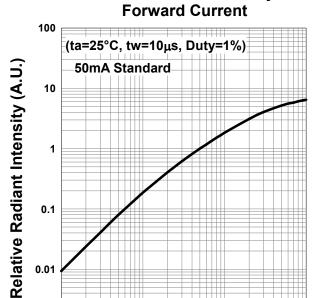
<sup>‡</sup> Radiant Intensity is measured by ANDO Optical Multi Meter AQ2140 & AQ2743.

**Relative Radiant Intensity -**

## **Typical Characteristic Curves**



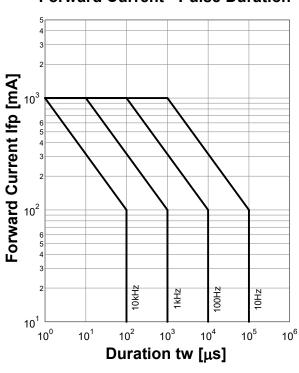




0.01

0.001

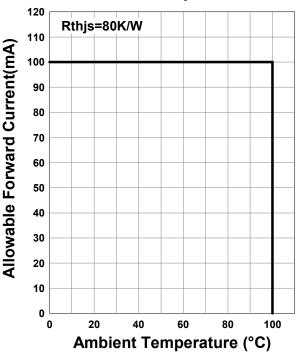
**Forward Current - Pulse Duration** 

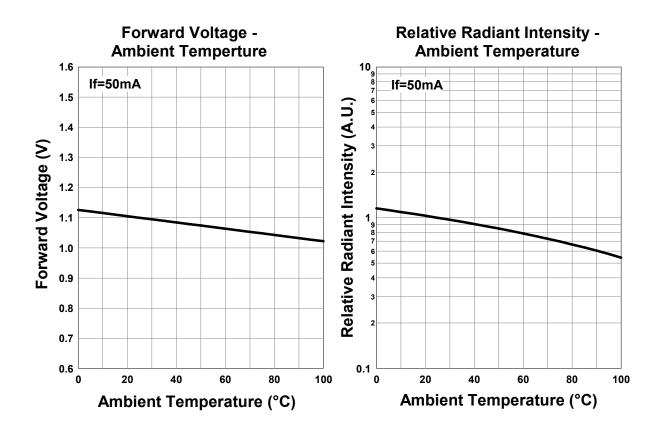


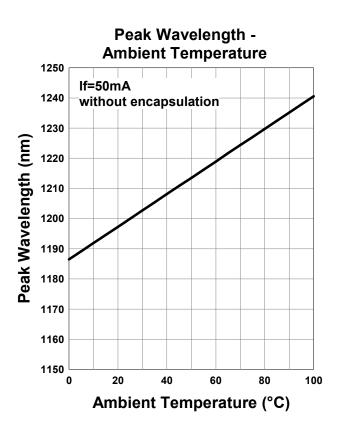


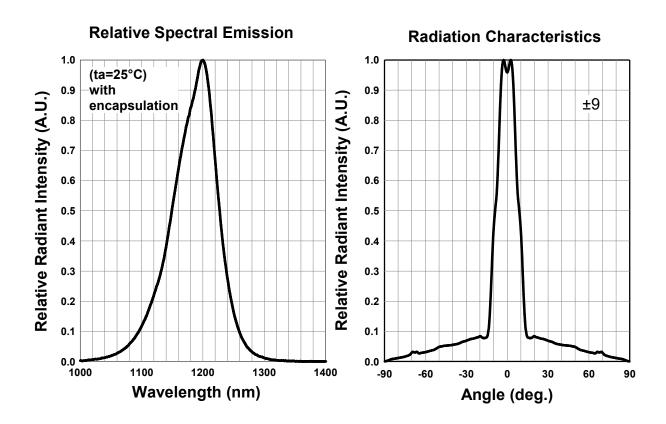
Forward Current (mA)

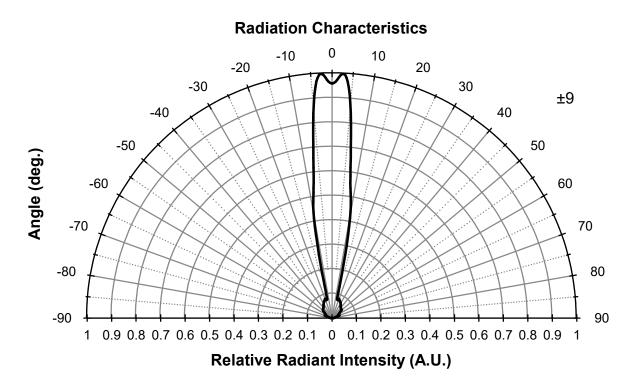
8 100





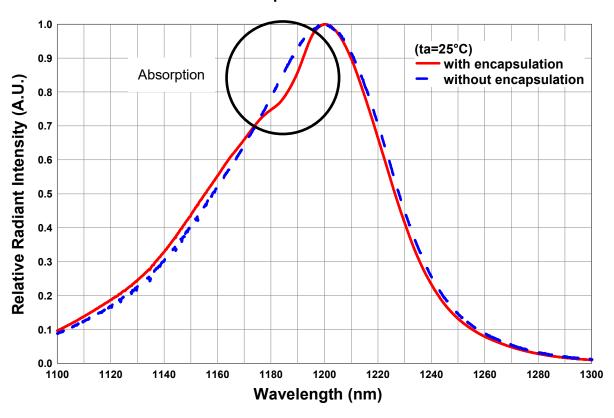




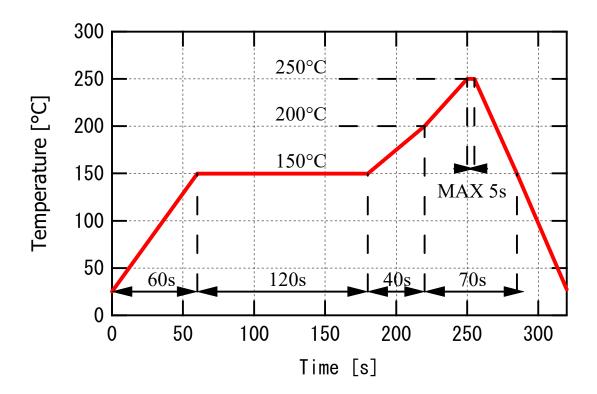


\*The absorption of lens resin changes spectral emission.

## **Relative Spectral Emission**



## **Recommended Reflow Soldering Profile**



## Wrapping

Moisture barrier bag aluminum laminated film with a desiccant to keep out the moisture absorption during the transportation and storage.

# SMD LED storage and handling precautions Storage Conditions before Opening a Moisture-Barrier Aluminum Bag

- Before opening a moisture-barrier aluminum bag, please store it at <30°C, <60%RH.</li>
- Please note that the maximum shelf life is 12 months under these conditions.

## Storage Conditions after Opening a Moisture-Barrier Aluminum Bag

- After opening a moisture-barrier aluminum bag, store the aluminum bag and silica gel in a desiccator.
- After opening the bag, please solder the LEDs within 72 hours in a room with 5 30°C, <50%RH.</li>
- Please put any unused, remaining LEDs and silica gel back in the same aluminum bag and then vacuum-seal the bag.
- It is recommended to keep the re-sealed bag in a desiccator at <30%RH.</li>
- The 72-hour- long floor life does not include the time while LEDs are stored in the moisture-barrier aluminum bag. However, we strongly recommend to solder the LEDs as soon as possible after opening the aluminum bag.

#### Notes about Re-sealing a Moisture-Barrier Aluminum Bag

When vacuum-sealing an opened aluminum bag, if you find the moisture-indicator of the silica gel
has changed to pink from blue (indicating a relative humidity of 30 % or more), please do not use
the unused LEDs, the aluminum bag, or the silica gel.

## Notes about Opening a Re-sealed Moisture-Barrier Aluminum Bag

 When opening a vacuumed and re-sealed aluminum bag in order to use the remaining LEDs stored in the bag, if you find that the moisture-indicator of the silica has changed to pink, please do not use the LEDs.

## SMT1200D-S1

#### **Disclaimer**

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